



## News Release

### **UNISEM OBTAINED SYNDICATED FINANCING FACILITIES OF RM400 MILLION FROM 6 MALAYSIAN BANKS**

**Kuala Lumpur, 27 September, 2006** - Unisem (M) Berhad (**Unisem**) today announced that it had on 26 September 2006 obtained Syndicated Financing Facilities of RM400 million (the "Facilities") from six Malaysian financial institutions with OCBC Bank (Malaysia) Berhad (**OCBC**) as the Mandated Lead Arranger and Sole Bookrunner. The Facilities comprise of a Syndicated Term Loan Facility of RM263 million and the Revolving Credit and Overdraft Facilities of RM137 million.

The purpose of the Facilities is to part-finance the capital expenditure and working capital requirements of Unisem.

Mr John Chia Sin Tet, Chairman/Managing Director commented, "This syndicated facility is a significant step towards positioning Unisem to be a preferred manufacturing partner for our clients and prospects. The facility will be used to fund expansion of our operations particularly into new areas of products such as wafer-level CSP, Flipchip and modules and high-end wafer level and Final Test services."

"It has been with the strong support of OCBC, the Mandated Lead Arranger and Sole Bookrunner, that this syndication has come to fruition. We are appreciative of the hard work, effort and commitment demonstrated by all the lenders. It amounts to an important acknowledgement of Unisem's financial and credit standing."

#### **About Unisem** [www.unisem.com.my](http://www.unisem.com.my)

Unisem (M) Berhad, a leading semiconductor packaging and test services company in Malaysia, has its main packaging and test facilities in Ipoh, Malaysia. With approximately 4,700 employees worldwide currently, Unisem has more than one million square feet of IC packaging and testing manufacturing space in Ipoh, Malaysia, Wales, United Kingdom and Chengdu, People's Republic of China and 20,000 square feet of wafer bumping facility in Ipoh, Malaysia. Unisem offers an integrated suite of packaging and test services for semiconductor companies such as wafer bump, wafer probe, wafer grinding, a wide range of leadframe and substrate IC packaging, high-end radio frequency and mix-signal test, tape & reel and drop-shipment services.